IGBT - Field Stop, Trench

650 V, 40 A

FGH40T65SH

Description

Using novel field stop IGBT technology, ON Semiconductor's new series of field stop 3rd generation IGBTs offer the optimum performance for solar inverter, UPS, welder, telecom, ESS and PFC applica-tions where low conduction and switching losses are essential.

Features

- Maximum Junction Temperature: $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- 100% of the Parts Tested for I_{LM} (Note 1)
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- This Device is Pb-Free and is RoHS Compliant

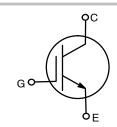
Applications

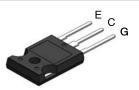
• Solar Inverter, UPS, Welder, Telecom, ESS, PFC



ON Semiconductor®

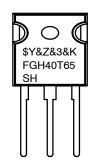
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TO-247-3LD CASE 340CH

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

FGH40T65SH = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ Unless Otherwise Noted)

Descri	Symbol	FGH40T65SH	Unit	
Collector to Emitter Voltage		V _{CES}	650	V
Gate to Emitter Voltage		V_{GES}	±20	V
Transient Gate to Emitter Voltage		1 [±30	V
Collector Current	T _C = 25°C	I _C	80	Α
Collector Current	T _C = 100°C	1 [40	Α
Pulsed Collector Current (Note 1)	T _C = 25°C	I _{LM}	120	Α
Pulsed Collector Current (Note 2)		I _{CM}	120	Α
Maximum Power Dissipation	T _C = 25°C	P_{D}	268	W
Maximum Power Dissipation	T _C = 100°C	1 [134	W
Operating Junction Temperature		TJ	-55 to +175	°C
Storage Temperature Range		T _{stg}	-55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. $V_{CC} = 400 \text{ V}$, $V_{GE} = 15 \text{ V}$, $I_{C} = 120 \text{ A}$, $R_{G} = 41,6 \Omega$, Inductive Load

2. Repetitive Rating: Pulse width limited by max. junction temperature.

THERMAL CHARACTERISTICS

Parameter	Symbol	FGH40T65SH	Unit
Thermal Resistance, Junction to Case, Max.	$R_{ heta JC}$	0.56	°C/W
Thermal Resistance, Junction to Ambient, Max.	$R_{ heta JA}$	40	°C/W

PACKAGE MARKING AND ORDERING INFORMATION

Top Mark	Part Number	Package	Reel Size	Tape Width	Quantity
FGH40T65SH	FGH40T65SH-F155	TO-247-3LD	1	-	30

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_C = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector to Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0 V, I _C = 1 mA	650	-	_	V
Temperature Coefficient of Breakdown Voltage	$\Delta BV_{CES}/\Delta T_{J}$	I _C = 1 mA, Reference to 25°C		0.6		V/°C
Collector Cut-Off Current	I _{CES}	V _{CE} = V _{CES} , V _{GE} = 0 V	-	-	250	μΑ
G-E Leakage Current	I _{GES}	V _{GE} = V _{GES} , V _{CE} = 0 V	=	-	±400	nA
ON CHARACTERISTICS						
G-E Threshold Voltage	$V_{GE(th)}$	I _C = 40 mA, V _{CE} = V _{GE}	4.0	5.5	7.5	V
Collector to Emitter Saturation Voltage	V _{CE(sat)}	I _C = 40 A, V _{GE} = 15 V	_	1.6	2.1	V
		I _C = 40 A, V _{GE} = 15 V, T _C = 175°C	_	2.14	_	V

ELECTRICAL CHARACTERISTICS OF THE IGBT (T_C = 25°C unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit		
DYNAMIC CHARACTERISTICS								
Input Capacitance	C _{ies}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	1995	_	pF		
Output Capacitance	C _{oes}]	-	70	-	pF		
Reverse Transfer Capacitance	C _{res}	1	-	23	_	pF		
SWITCHING CHARACTERISTICS								
Turn-On Delay Time	t _{d(on)}	$V_{CC} = 400 \text{ V}, I_C = 40 \text{ A},$	-	19.2	_	ns		
Rise Time	t _r	$R_G = 6 \Omega$, $V_{GE} = 15 V$, Inductive Load, $T_C = 25^{\circ}C$	_	34.4	_	ns		
Turn-Off Delay Time	t _{d(off)}	7	-	65.6	-	ns		
Fall Time	t _f		-	9.6	-	ns		
Turn-On Switching Loss	E _{on}		-	1010	-	μJ		
Turn-Off Switching Loss	E _{off}		-	297	-	μJ		
Total Switching Loss	E _{ts}		-	1307	-	μJ		
Turn-On Delay Time	t _{d(on)}	$V_{CC} = 400 \text{ V, } I_{C} = 40 \text{ A,}$ $R_{G} = 6 \Omega, V_{GE} = 15 \text{ V,}$ Inductive Load, $T_{C} = 175^{\circ}\text{C}$	-	18.4	-	ns		
Rise Time	t _r		-	32.8	_	ns		
Turn-Off Delay Time	t _{d(off)}	1	-	71.2	_	ns		
Fall Time	t _f	1	-	14.4	_	ns		
Turn-On Switching Loss	E _{on}	1	-	1390	_	μJ		
Turn-Off Switching Loss	E _{off}		-	541	_	μJ		
Total Switching Loss	E _{ts}		-	1931	_	μJ		
Total Gate Charge	Qg	V _{CC} = 400 V, I _C = 40 A,	-	72.2	_	nC		
Gate to Emitter Charge	Q _{ge}	- V _{GE} = 15 V	-	13.5	_	nC		
Gate to Collector Charge	Q _{gc}	1	-	28.5	_	nC		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

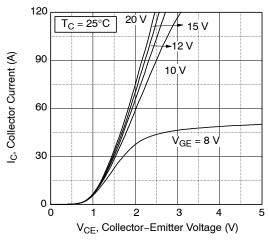


Figure 1. Typical Output Characteristics

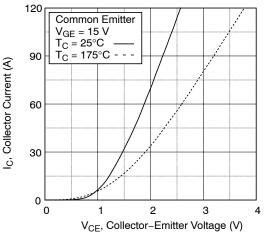


Figure 3. Typical Saturation Voltage Characteristics

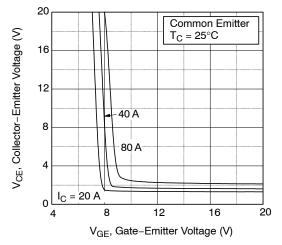


Figure 5. Saturation Voltage vs V_{GE}

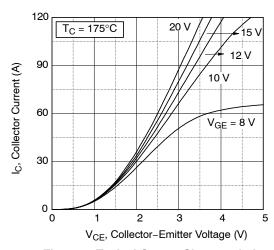


Figure 2. Typical Output Characteristics

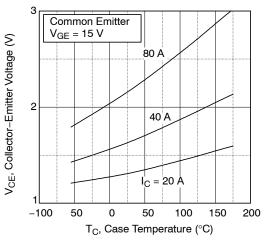


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

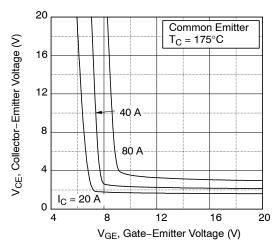


Figure 6. Saturation Voltage vs V_{GE}

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

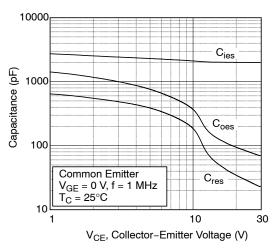


Figure 7. Capacitance Characteristics

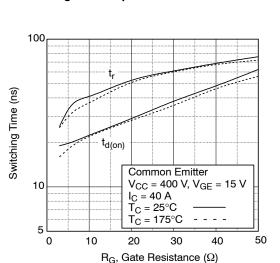


Figure 9. Turn-On Characteristics vs. Gate Resistance

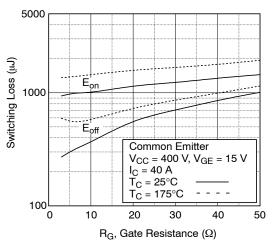


Figure 11. Switching Loss vs. Gate Resistance

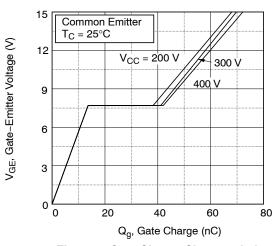


Figure 8. Gate Charge Characteristics

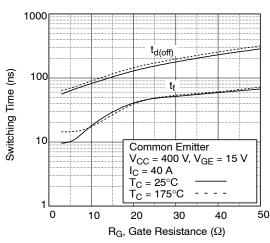


Figure 10. Turn-Off Characteristics vs. Gate Resistance

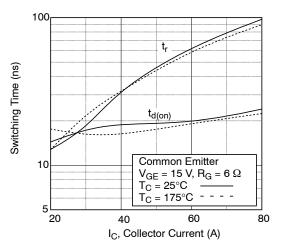


Figure 12. Turn-On Characteristics vs. Collector Current

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

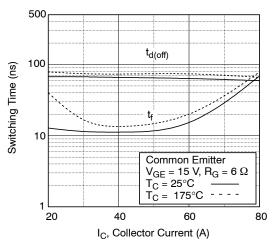


Figure 13. Turn-Off Characteristics vs. Collector Current

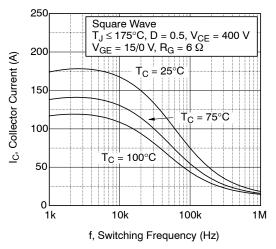


Figure 15. Load Current vs. Frequency

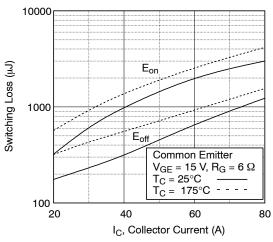


Figure 14. Switching Loss vs. Collector Current

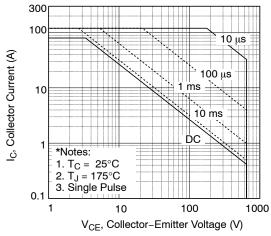


Figure 16. SOA Characteristics

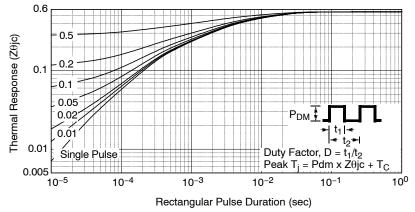
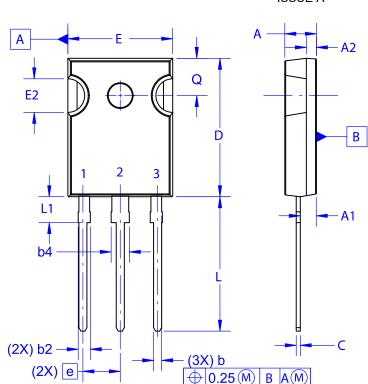


Figure 17. Transient Thermal Impedance of IGBT

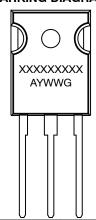
TO-247-3LD CASE 340CH **ISSUE A**





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC **MARKING DIAGRAM***



XXXX = Specific Device Code

= Assembly Location

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

	DATE	DATE 09 OCT 2019		
Ø P —		P1 D2		
S E1 —	2	D1		
		<u>.</u>		

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.29	2.475	2.66		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.61	6.73	6.85		

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